



## SSC8634GN4

### N and P-Channel Enhancement Mode Power MOSFET

#### ➤ Features

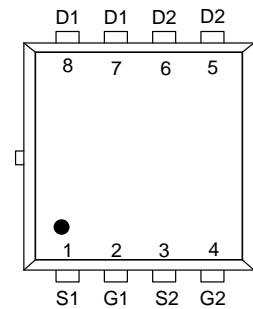
##### N-Channel

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$
30V	$\pm 20V$	15m $\Omega$ @10V	27A
		24m $\Omega$ @4V5	

##### P-Channel

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$
-30V	$\pm 20V$	18m $\Omega$ @-10V	-26A
		26m $\Omega$ @-4V5	

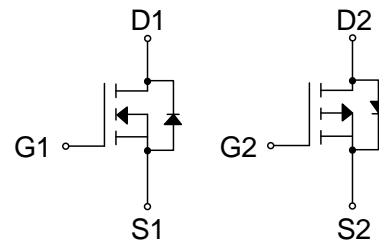
#### ➤ Pin configuration



**PDFN3.3X3.3-8L (Top View)**

#### ➤ Description

The SSC8634GN4 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.



**Pin Configuration**

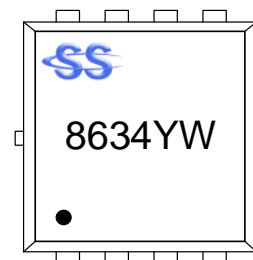
**100% UIS +  $\Delta V_{DS}$  +  $R_g$  Tested!**

#### ➤ Applications

- PWM Applications
- Load Switch
- DC-DC Converters
- Wireless Chargers

#### ➤ Ordering Information

Device	Package	Shipping
SSC8634GN4	PDFN3.3X3.3-8L	5000/Reel



**Marking**

(YW: Internal Traceability Code)



➤ **Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-to-Source Voltage		$V_{DSS}$	30	-30	V
Gate-to-Source Voltage		$V_{GSS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current <sup>a</sup>	$T_A=25^\circ\text{C}$	$I_D$	27	-26	A
	$T_A=100^\circ\text{C}$		14	-13.6	A
Pulsed Drain Current <sup>b</sup>		$I_{DM}$	108	-100	A
Power Dissipation <sup>a</sup>		$P_{DSM}$	2.6	2.6	W
Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse		$I_{AS}$	10	16	A
Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse		$E_{AS}$	25	64	mJ
Power Dissipation <sup>c</sup>	$T_A=25^\circ\text{C}$	$P_D$	21	20	W
	$T_A=100^\circ\text{C}$		8.2	8	W
Operation junction temperature		$T_J$	-55 to 150	-55 to 150	$^\circ\text{C}$
Storage temperature range		$T_{STG}$	-55 to 150	-55 to 150	$^\circ\text{C}$

➤ **Thermal Resistance Ratings ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	N-Channel	P-Channel	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	47	48	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	6	6.25	

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.



➤ **N-Channel Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	1	1.8	2.5	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 7A		15	20	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A		24	31	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 6A		10		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A		0.76	1.3	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz		715		pF
Output Capacitance	C <sub>OSS</sub>			81		
Reverse Transfer Capacitance	C <sub>RSS</sub>			67		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 8A		14		nC
Gate to Source Charge	Q <sub>GS</sub>			2.2		
Gate to Drain Charge	Q <sub>GD</sub>			1.82		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, R <sub>L</sub> = 10Ω, R <sub>GEN</sub> = 6Ω		8.4		ns
Rise Time	T <sub>r</sub>			7.7		
Turn-off Delay Time	T <sub>D(OFF)</sub>			16.8		
Fall Time	T <sub>f</sub>			5.5		

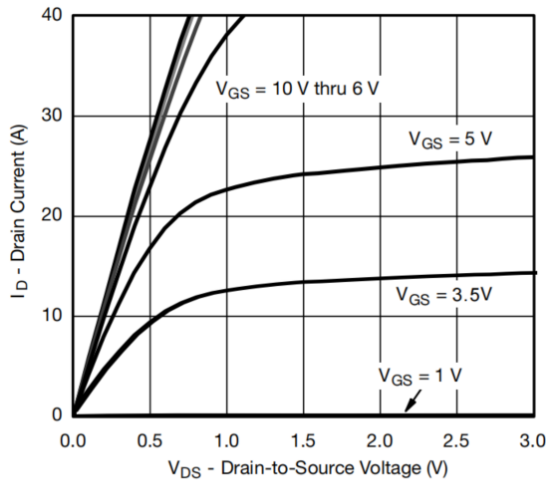


➤ **P-Channel Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

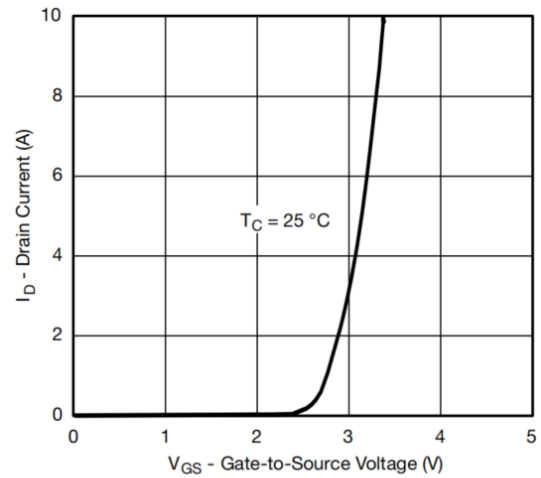
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250uA	-1	-1.6	-2.5	V
Drain-Source On-Resistance	R <sub>Ds(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -7A		15	20	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -5A		18	23	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V			-1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -4A		15		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A		-0.76	-1.3	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1MHz		1300		pF
Output Capacitance	C <sub>OSS</sub>			182		
Reverse Transfer Capacitance	C <sub>RSS</sub>			161		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = -15V, V <sub>DS</sub> = -10V, I <sub>D</sub> = -6A		25.5		nC
Gate to Source Charge	Q <sub>GS</sub>			4.5		
Gate to Drain Charge	Q <sub>GD</sub>			6.12		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = -15V, V <sub>DS</sub> = -10V, R <sub>L</sub> = 10Ω, R <sub>GEN</sub> = 6Ω		7.8		ns
Rise Time	T <sub>r</sub>			34.4		
Turn-off Delay Time	T <sub>D(OFF)</sub>			49.4		
Fall Time	T <sub>f</sub>			11		



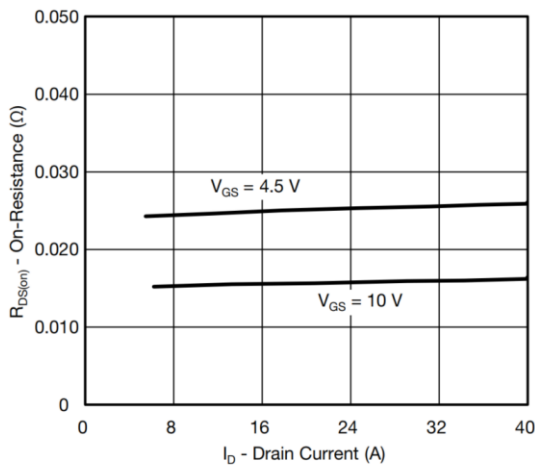
## ➤ N-Channel Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)



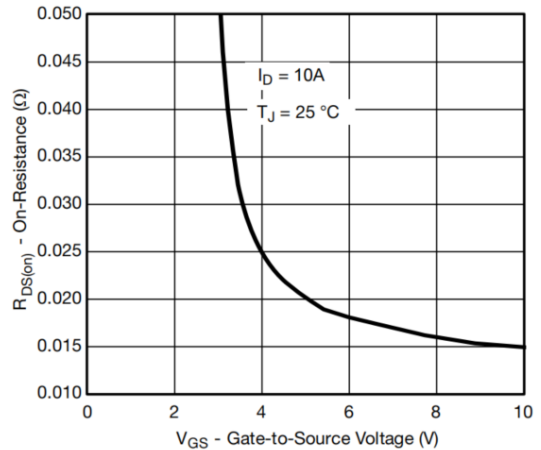
**Output Characteristics**



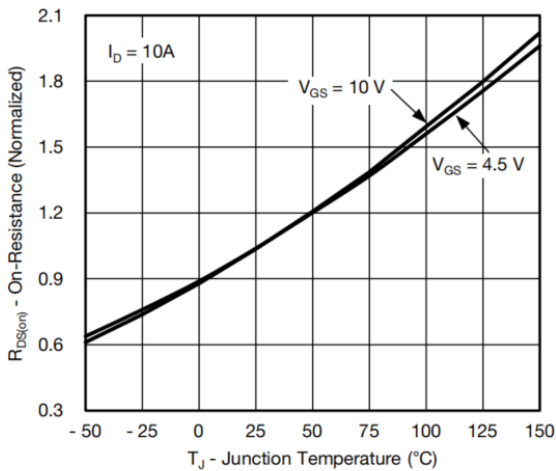
**Transfer Characteristics**



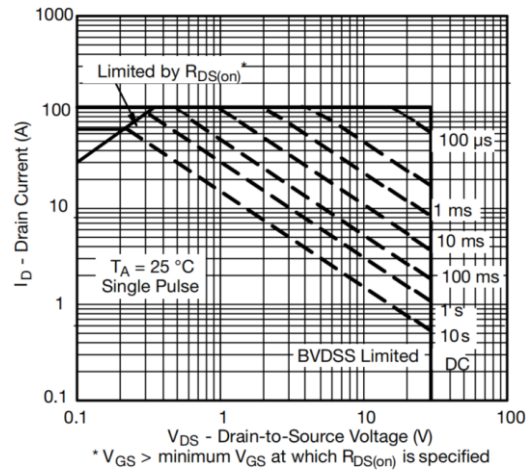
**On-Resistance vs. Drain Current and Gate Voltage**



**On-Resistance vs. Gate-to-Source Voltage**



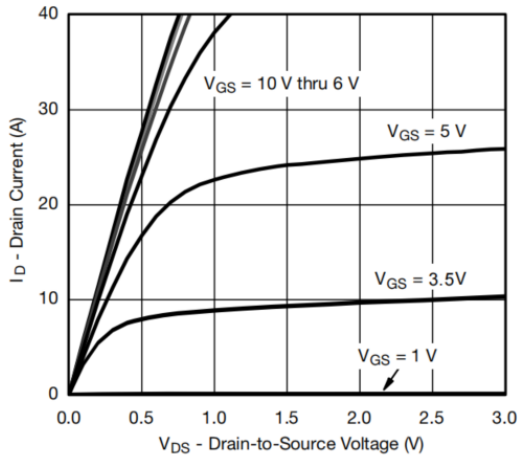
**On-Resistance vs. Junction Temperature**



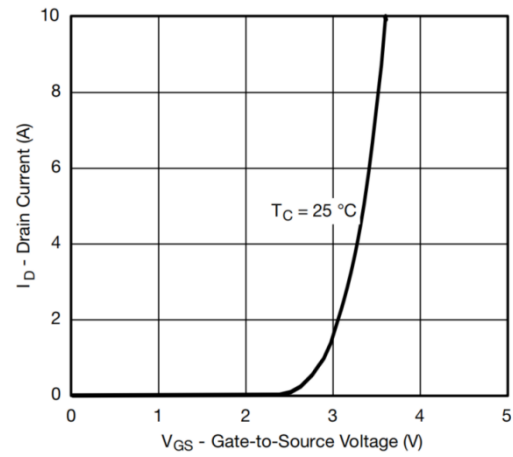
**Safe Operating Area, Junction-to-Ambient**



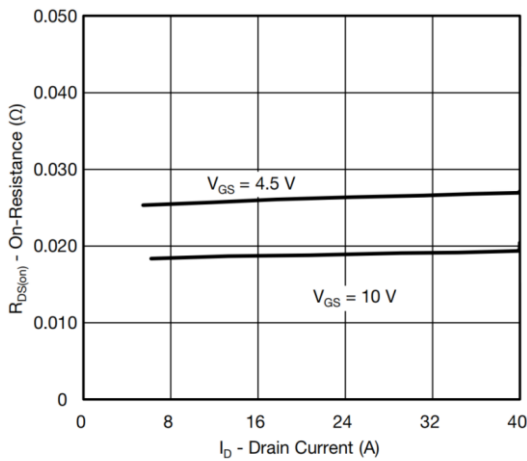
## ➤ P-Channel Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)



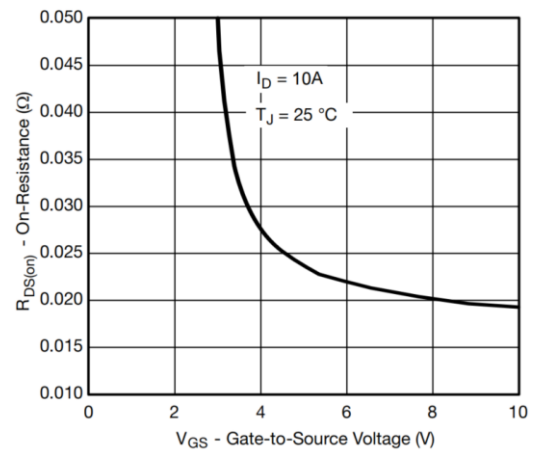
**Output Characteristics**



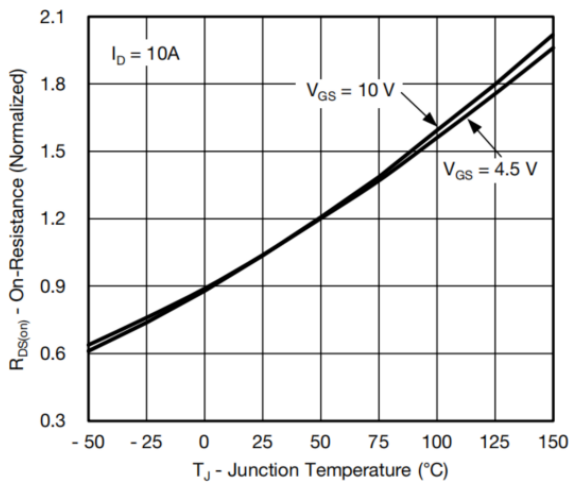
**Transfer Characteristics**



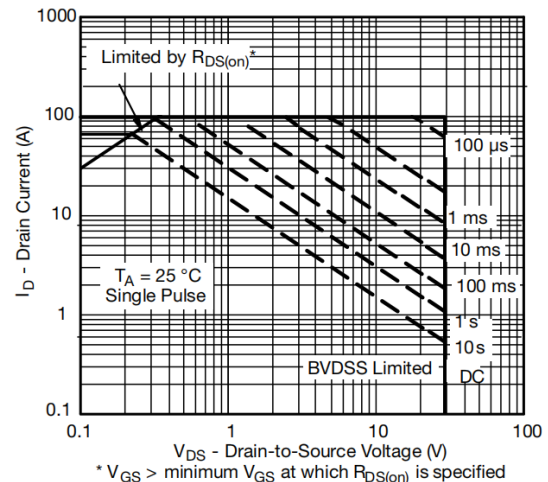
**On-Resistance vs. Drain Current and Gate Voltage**



**On-Resistance vs. Gate-to-Source Voltage**

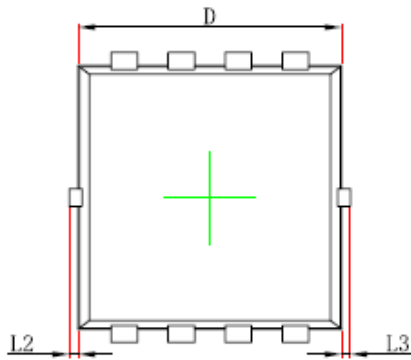


**On-Resistance vs. Junction Temperature**

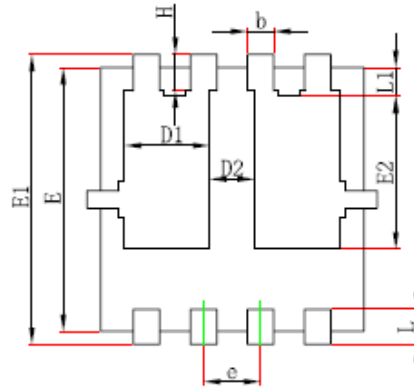


**Safe Operating Area, Junction-to-Ambient**

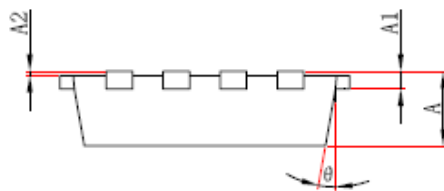
## ➤ Package Information



Top View  
[顶视图]



Bottom View  
[背视图]



Side View  
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°



## DISCLAIMER

SSCSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. SSCSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENCE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

THE GRAPHS PROVIDED IN THIS DOCUMENT ARE STATISTICAL SUMMARIES BASED ON A LIMITED NUMBER OF SAMPLES AND ARE PROVIDED FOR INFORMATIONAL PURPOSE ONLY. THE PERFORMANCE CHARACTERISTICS LISTED IN THEM ARE NOT TESTED OR GUARANTEED. IN SOME GRAPHS, THE DATA PRESENTED MAY BE OUTSIDE THE SPECIFIED OPERATING RANGE (E.G. OUTSIDE SPECIFIED POWER SUPPLY RANGE) AND THEREFORE OUTSIDE THE WARRANTED RANGE.

OUR PRODUCT SPECIFICATIONS ARE ONLY VALID IF OBTAINED THROUGH THE COMPANY'S OFFICIAL WEBSITE, CRM SYSTEM, OR OUR SALES PERSONNEL CHANNELS. IF CHANGES OR SPECIAL VERSIONS ARE INVOLVED, THEY MUST BE STAMPED WITH A QUALITY SEAL AND MARKED WITH A SPECIAL VERSION NUMBER TO BE VALID.